

Claims

1. A semiconductor apparatus comprising:

a housing in which device mounting portions are respectively formed on both one surface side and the other surface side thereof;

a first device mounted in the device mounting portion on one surface side of this housing;

a second device mounted in the device mounting portion on the other surface side of the housing; and

a plurality of leads having pad portions for wire bonding, supported by the housing while exposing those pad portions to the device mounting portions, and connected through wires to the first device or second device in the device mounting portions, wherein

said pad portions of at least one lead among the plurality of leads are exposed to the device mounting portions in the position relation alternate with each other on the one surface side and the other surface side of the housing, and

this exposed portion serves as the connection portion of the wire bonding.

2. The semiconductor apparatus as cited in claim 1, characterized in which;

said pad portion of at least one lead is formed larger than the pad portion of the other lead.

3. (Added) A semiconductor apparatus characterized by comprising:

a housing in which device mounting portions are respectively formed on both one surface side and the other

surface side,;

a first device mounted in the device mounting portion on said one surface side of this housing;

a second device mounted in the device mounting portion on said the other surface side of the housing; and

a plurality of leads having pad portions for wire bonding, being supported by the housing while exposing those pad portions to the device mounting portions, and being connected through wires to the first device or second device in the device mounting portions,

wherein the pad portions of at least one lead among the plurality of leads are exposed to the device mounting portions in the position relation alternate with each other, on the one surface side and the other surface side of the housing, and

this exposed portion serves as the connection portion of the wire bonding.

4. (Added) A semiconductor apparatus characterized by comprising:

a housing in which device mounting portions are respectively formed on both one surface side and the other surface side thereof;

a first device mounted in the device mounting portion on said one surface side of this housing;

a second device mounted in the device mounting portion on said the other surface side of the housing; and

a plurality of leads having pad portions for wire bonding, supported by the housing while exposing those pad portions to the device mounting portions, and connected through wires to the first device or second device in the device mounting portions,

wherein the pad portions of at least one lead among the

plurality of leads are exposed to the device mounting portions in the position relation alternate with each other, on the one surface side and the other surface side of the housing, and

this exposed portion serves as the connection portion of the wire bonding.